imall

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832 Email & Skype: info@chipsmall.com Web: www.chipsmall.com Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



Data sheet MTi 1-series



3D AHRS/VRU/IMU module

Document MT0512P, Revision D, 5 Dec 2016

Features

- Full-featured AHRS on 12.1 x 12.1 mm module
- Roll/pitch accuracy (dynamic) 1.0 deg
- Heading accuracy 2.0 deg
- Minimal requirements on host processor
- Uniform interface over product lifetime
 - No hardware/software interface changes
 No EOL
- Always best-in-class inertial sensors incorporated
- Industry-leading signal processing pipeline (AttitudeEngineTM) with vibration-rejection
- Robust and accurate orientation algorithm (XKF3TM)
- API-compatible with all Xsens' Motion Trackers
 Drivers and examples on ARM[®] mbedTM
- Low power (45 mW @ 3.0V)
- PLCC28-compatible PCB (12.1 x 12.1 x 2.6 mm)

Applications

- Miniature aerial vehicles
- Heavy machinery/agriculture
- Robotics, pedestrian dead-reckoning
- Industrial grade VR/AR, HMD's and handheld devices

Related Resources

- www.xsens.com/MTi-1-series
- MTi 1-series DK User Manual (MT0513P)
- MT Low Level Communication Protocol Documentation (MT0101P)
- MTi White Paper: Next generation Xsens Motion Trackers for Industrial applications

Description

The MTi 1-series is a module outputting 3D orientation, 3D rate of turn, 3D accelerations, and 3D magnetic field, depending on the product configuration. It is available as an Inertial Measurement Unit (IMU), Vertical Reference Unit (VRU) or Attitude and Heading Reference System (AHRS).

This fully-functional self-contained module is easy to design in with limited hardware components to be added. The fully documented, industry-standard communication protocol allows for customization of the data message in terms of data, frequency and output format. Signals are fully processed onboard, requiring very little resources from the host and is well suited for applications in simple MCU-operated environments. The host can read-out the data over SPI, I²C or UART.

With a roll/pitch accuracy of 1.0° RMS and yaw accuracy of 2° RMS under dynamic conditions, the output is excellent for control and stabilization of any object and navigation of e.g. unmanned vehicles.

Product Output	MTi-1 IMU	MTi-2 VRU	MTi-3 AHRS
Motion data	•	•	•
Magnetic field	•	•	•
Roll/pitch		•	•
Heading tracking		•	•
Referenced yaw			•

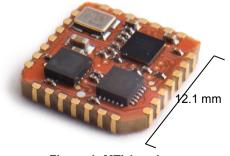


Figure 1: MTi 1-series

1 Table of Contents

2	GENER	L INFORMATION	3
		RING INFORMATION	
		CIAGRAM	
		AL APPLICATION	
		ONFIGURATION	
	-	IAP ESCRIPTIONS	-
		ESCRIPTIONS	
	2.7.1	Peripheral Interface Architecture	
	2.7.2	Xbus Protocol	7
	2.7.3	MTSSP Synchronous Serial Protocol	
	2.7.4	I ² C	
	2.7.5	SPI	
	2.7.6 2.7.7	UART half duplex UART full duplex with RTS/CTS flow control	
		MMENDED EXTERNAL COMPONENTS	
3			
		L-SERIES CONFIGURATIONS	
	3.1.1	MTi-1 IMU	
	3.1.2 3.1.3	MTi-2 VRU MTi-3 AHRS	
	3.2.1	Strapdown integration	-
	3.2.2	XKF3™ Sensor Fusion Algorithm	
	3.2.3	Frames of reference used in MTi 1-series	20
4	3D ORII	NTATION AND PERFORMANCE SPECIFICATIONS	21
	4.1 3D C	RIENTATION SPECIFICATIONS	21
		RENTATION SPECIFICATIONS	
	4.Z JEINS	JRS SPECIFICATIONS	
F			
5	SENSOF	CALIBRATION	23
5 6	SENSOF		23
	SENSOF SYSTEM 6.1 INTER	CALIBRATION AND ELECTRICAL SPECIFICATIONS	23 24 24
	SENSOF SYSTEM 6.1 INTEF 6.2 SYSTE	CALIBRATION AND ELECTRICAL SPECIFICATIONS FACE SPECIFICATIONS M SPECIFICATIONS	23 24 24 24
	SENSOF SYSTEM 6.1 INTEF 6.2 SYSTE 6.3 ELECT	CALIBRATION	23 24 24 24 25
	SENSOF SYSTEM 6.1 INTER 6.2 SYSTE 6.3 ELEC 6.4 ABSC	CALIBRATION	23 24 24 24 25 25
6	SENSOF SYSTEM 6.1 INTER 6.2 SYSTE 6.3 ELECT 6.4 ABSC 6.5 COM	CALIBRATION	23 24 24 25 25 25
	SENSOF SYSTEM 6.1 INTER 6.2 SYSTE 6.3 ELECT 6.4 ABSC 6.5 COM	CALIBRATION	23 24 24 24 25 25
6	SENSOF SYSTEM 6.1 INTER 6.2 SYSTE 6.3 ELECT 6.4 ABSC 6.5 COM MTI 1-S	CALIBRATION	23 24 24 24 25 25 25 25 26
6	SENSOF SYSTEM 6.1 INTER 6.2 SYSTE 6.3 ELEC 6.4 ABSC 6.5 COM MTI 1-S 7.1 7.2 OUTF	CALIBRATION	23 24 24 25 25 25 26 26 26
6	SENSOF SYSTEM 6.1 INTER 6.2 SYSTE 6.3 ELECT 6.4 ABSC 6.5 COM MTI 1-S 7.1 7.2 OUTF 7.3 MTE	CALIBRATION	23 24 24 25 25 25 26 26 26 28
6	SENSOF SYSTEM 6.1 INTER 6.2 SYSTE 6.3 ELEC 6.4 ABSC 6.5 COM MTI 1-S 7.1 7.2 OUTF 7.3 MTE 7.4 SYNC	CALIBRATION AND ELECTRICAL SPECIFICATIONS FACE SPECIFICATIONS FACE SPECIFICATIONS RICAL SPECIFICATIONS LUTE MAXIMUM RATINGS LUTE MAXIMUM RATINGS ERIES SETTINGS AND OUTPUTS AGE STRUCTURE UT SETTINGS ATA2 IRONIZATION AND TIMING	23 24 24 25 25 26 26 26 26 28 28 29
6	SENSOF SYSTEM 6.1 INTER 6.2 SYSTE 6.3 ELEC 6.4 ABSC 6.5 COM MTI 1-S 7.1 7.2 OUTF 7.3 MTE 7.4 SYNC	CALIBRATION	23 24 24 25 25 26 26 26 26 28 28 29
6	SENSOF SYSTEM 6.1 INTER 6.2 SYSTE 6.3 ELEC 6.4 ABSC 6.5 COM MTI 1-S 7.1 7.2 OUTF 7.3 MTE 7.4 SYNC MAGNE 8.1	CALIBRATION	23 24 24 25 25 25 26 26 26 27 28 29 30 30
6	SENSOF SYSTEM 6.1 INTER 6.2 SYSTE 6.3 ELEC 6.4 ABSC 6.5 COM MTI 1-S 7.1 7.2 OUTF 7.3 MTE 7.4 SYNC MAGNE 8.1	CALIBRATION	23 24 24 25 25 25 26 26 26 27 28 29 30 30
6	SENSOF SYSTEM 6.1 INTER 6.2 SYSTE 6.3 ELEC 6.4 ABSC 6.5 COM MTI 1-S 7.1 7.2 OUTE 7.3 MTE 7.4 SYNC MAGNE 8.1 8.2 ACTIV	CALIBRATION	23 24 24 25 25 25 26 26 27 28 29 30 30 30 30 30 30 30 30
6 7 8	SENSOF SYSTEM 6.1 INTER 6.2 SYSTE 6.3 ELEC 6.4 ABSC 6.5 COM MTI 1-S 7.1 MESS 7.2 OUTF 7.3 MTE 7.4 SYNC MAGNE 8.1 MAG 8.2 ACTIV	CALIBRATION AND ELECTRICAL SPECIFICATIONS FACE SPECIFICATIONS M SPECIFICATIONS RICAL SPECIFICATIONS RICAL SPECIFICATIONS LUTE MAXIMUM RATINGS ULATE ERIES SETTINGS AND OUTPUTS AGE STRUCTURE UT SETTINGS AAAD ATA2 HRONIZATION AND TIMING TIC INTERFERENCE NETIC FIELD MAPPING E HEADING STABILIZATION (AHS)	23 24 24 25 25 25 26 26 26 27 28 29 30 30 30 31
6 7 8	SENSOF SYSTEM 6.1 INTER 6.2 SYSTE 6.3 ELEC 6.4 ABSC 6.5 COM MTI 1-S 7.1 MESS 7.2 OUTF 7.3 MTE 7.2 OUTF 7.3 MTE 7.4 SYNC MAGNE 8.1 MAG 8.2 ACTIV PACKAC 9.1 PACK	CALIBRATION AND ELECTRICAL SPECIFICATIONS FACE SPECIFICATIONS M SPECIFICATIONS RICAL SPECIFICATIONS LUTE MAXIMUM RATINGS PLIANCE ERIES SETTINGS AND OUTPUTS AGE STRUCTURE UT SETTINGS ATA2 HRONIZATION AND TIMING TIC INTERFERENCE NETIC FIELD MAPPING E HEADING STABILIZATION (AHS).	23 24 24 25 25 25 26 26 26 27 28 29 30 30 31 31
6 7 8	SENSOF SYSTEM 6.1 INTER 6.2 SYSTE 6.3 ELEC 6.4 ABSC 6.5 COM MTI 1-S 7.1 MESS 7.2 OUTE 7.3 MTE 7.2 OUTE 7.3 MTE 7.4 SYNC MAGNE 8.1 MAG 8.2 ACTIV PACKAO 9.1 PACK 9.2 MOU	CALIBRATION	23 24 24 25 25 25 26 26 26 27 28 29 30 30 30 31 31
6 7 8	SENSOF SYSTEM 6.1 INTER 6.2 SYSTE 6.3 ELEC 6.4 ABSC 6.5 COM MTI 1-S 7.1 MESS 7.2 OUTE 7.3 MTE 7.2 OUTE 7.3 MTE 7.4 SYNC MAGNE 8.1 MAG 8.2 ACTIV PACKAO 9.1 PACK 9.2 MOU	CALIBRATION AND ELECTRICAL SPECIFICATIONS FACE SPECIFICATIONS FACE SPECIFICATIONS RICAL SPECI	23 24 24 25 25 25 26 26 26 27 28 29 30 30 30 31 31 31 32 32
6 7 8	SENSOF SYSTEM 6.1 INTEF 6.2 SYSTE 6.3 ELEC 6.4 ABSC 6.5 COM MTI 1-S 7.1 MESS 7.2 OUTF 7.3 MTE 7.2 OUTF 7.3 MTE 7.4 SYNC MAGNE 8.1 MAG 8.2 ACTIN PACKAC 9.1 PACK 9.3 PACK 9.3.1 9.3.2	CALIBRATION	23 24 24 25 25 25 26 26 26 26 26 26 26 26 20 30 30 30 31 31 31 31 32 32 32 32
6 7 8	SENSOF SYSTEM 6.1 INTEF 6.2 SYSTE 6.3 ELEC 6.4 ABSC 6.5 COM MTI 1-S 7.1 MESS 7.2 OUTF 7.3 MTE 7.2 OUTF 7.3 MTE 7.4 SYNC MAGNE 8.1 MAG 8.2 ACTIN PACKAC 9.1 PACK 9.3 PACK 9.3.1 9.3.2	CALIBRATION AND ELECTRICAL SPECIFICATIONS FACE SPECIFICATIONS FACE SPECIFICATIONS RICAL SPECI	23 24 24 25 25 25 26 26 26 26 26 26 26 26 20 30 30 30 31 31 31 31 32 32 32 32
6 7 8	SENSOF SYSTEM 6.1 INTER 6.2 SYSTE 6.3 ELECT 6.4 ABSC 6.5 COM MTI 1-S 7.1 MESS 7.2 OUTF 7.3 MTE 7.4 SYNC MAGNE 8.1 MAG 8.2 ACTIV PACKAC 9.1 PACK 9.3 PACK 9.3.1 9.3.2 9.4 REFLC	CALIBRATION	23 24 24 25 25 25 26 26 26 27 28 29 30 30 30 31 31 31 31 31 31 32 32 33 34
6 7 8 9	SENSOF SYSTEM 6.1 INTEF 6.2 SYSTE 6.3 ELEC 6.4 ABSC 6.5 COM MTI 1-S 7.1 MESS 7.2 OUTF 7.3 MTE 7.4 SYNC MAGNE 8.1 MAG 8.2 ACTIV PACKAC 9.1 PACK 9.2 MOU 9.3 PACK 9.3 PACK 9.3.1 9.3.2 9.4 REFLO	CALIBRATION	23 24 24 25 25 25 26 26 26 26 26 26 26 26 20 30 30 30 30 31 31 31 31 31 32 32 33 34 35
6 7 8 9	SENSOF SYSTEM 6.1 INTEF 6.2 SYSTE 6.3 ELEC 6.4 ABSC 6.5 COM MTI 1-S 7.1 MESS 7.2 OUTF 7.3 MTE 7.2 OUTF 7.3 MTE 7.4 SYNC MAGNE 8.1 MAG 8.2 ACTIV PACKAC 9.1 PACK 9.2 MOU 9.3 PACK 9.3 PACK 9.1 PACK 9.3 PACK 9.3 PACK 9.3 PACK 9.3 PACK 9.3 PACK 9.3 PACK 9.1 PACK 9.3 PACK 9.1 PACK 9.1 PACK 9.1 PACK 9.2 MOU 9.3 PACK 9.1 PACK	CALIBRATION	23 24 24 25 25 25 26 26 26 26 26 26 26 26 20 30 30 30 30 31 31 31 32 32 33 34 35 35

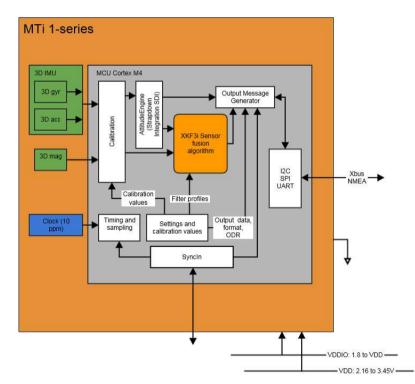
www.xsens.com

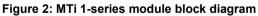
2 General information

2.1 Ordering Information

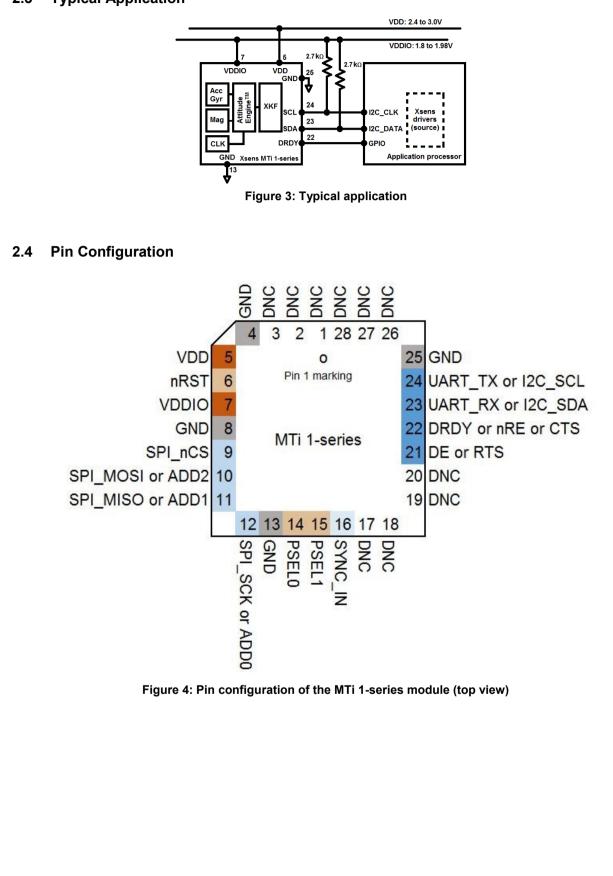
Part Number	Output	Package	Packing Method
MTI-1-8A7G6T	IMU; inertial data	PCB, JEDEC-PLCC-28 compatible	Tray of 20
MTI-2-8A7G6T	VRU; inertial data, roll/pitch (referenced), yaw (unreferenced)	PCB, JEDEC-PLCC-28 compatible	Tray of 20
MTI-3-8A7G6T	AHRS; inertial data, roll/pitch/yaw	PCB, JEDEC-PLCC-28 compatible	Tray of 20
MTI-1-8A7G6R	IMU; inertial data	PCB, JEDEC-PLCC-28 compatible	Reel of 250
MTI-2-8A7G6R	VRU; inertial data, roll/pitch (referenced), yaw (unreferenced)	PCB, JEDEC-PLCC-28 compatible	Reel of 250
MTI-3-8A7G6R	AHRS; inertial data, roll/pitch/yaw	PCB, JEDEC-PLCC-28 compatible	Reel of 250
MTi-3-8A7G6-DK	Development kit for MTi 1-series, including MTi-3-8A7G6		Single unit

2.2 Block Diagram





2.3 Typical Application



2.5 Pin map

The pin map depends on the peripheral selection. See section 2.7 on how to set the peripherals.

	PSEL: I ² C	PSEL: SPI	PSEL: UART half duplex	PSEL: UART full duplex
1	DNC	DNC	DNC	DNC
2	DNC	DNC	DNC	DNC
3	DNC	DNC	DNC	DNC
4	GND	GND	GND	GND
5	VDD	VDD	VDD	VDD
6	nRST	nRST	nRST	nRST
7	VDDIO	VDDIO	VDDIO	VDDIO
8	GND	GND	GND	GND
9	DNC	SPI_NCS	DNC	DNC
10	ADD2 ¹	SPI_MOSI	DNC	DNC
11	ADD1	SPI_MISO	DNC	DNC
12	ADD0	SPI_SCK	DNC	DNC
13	GND	GND	GND	GND
14	PSEL0	PSEL0	PSEL0	PSEL0
15	PSEL1	PSEL1	PSEL1	PSEL1
16	SYNC_IN	SYNC_IN	SYNC_IN	SYNC_IN
17	DNC	DNC	DNC	DNC
18	DNC	DNC	DNC	DNC
19	DNC	DNC	DNC	DNC
20	DNC	DNC	DNC	DNC
21	DNC	DNC	DE	RTS
22	DRDY	DRDY	nRE	CTS ²
23	I2C_SDA	DNC	UART_RX	UART_RX
24	I2C_SCL	DNC	UART_TX	UART_TX
25	GND	GND	GND	GND
26	DNC	DNC	DNC	DNC
27	DNC	DNC	DNC	DNC
28	DNC	DNC	DNC	DNC

¹ I²C addresses, see Table 2: List of I²C addresses ² CTS cannot be left unconnected if the interface is set to UART full duplex. If HW flow control is not used, connect to GND.

Name	Туре	Description	
Power Interfa	ce		
VDD	Power	Power supply voltage for sensing elements	
VDDIO	Power	Digital I/O supply voltage	
Controls			
PSEL0		These pins determine the signal interface. See table below. Note that when the	
PSEL1	Selection pins	PSEL0/PSEL1 is not connected, its value is 1. When PSEL0/PSEL1 is connected to GND, its value is 0	
nRST		Active low reset pin. Only drive with an open drain output or momentary (tactile) switch to GND. During normal operation this pin must be left floating, because this line is also used for internal resets. This pin has an internal weak pull-up to VDDIO.	
ADD2			
ADD1	Selection pins	I ² C address selection lines	
ADD0	1		
Signal Interfa	се		
I2C_SDA	I ² C interface	I ² C serial data	
I2C_SCL	1-C Intenace	I ² C serial clock	
SPI_nCS		SPI chip select (active low)	
SPI_MOSI	SPI interface	SPI serial data input (slave)	
SPI_MISO	OFFICE	SPI serial data output (slave)	
SPI_SCK		SPI serial clock	
RTS		Hardware flow control in UART full duplex mode (Ready-to-Send)	
CTS		Hardware flow control in UART full duplex mode (Clear-to-Send). If flow control is not used connect to GND	
nRE	UART	Receiver control signal in UART half duplex mode	
DE	interface	Transmitter control signal in UART half duplex mode	
UART_RX		Receiver data input	
UART_TX		Transmitter data output	
SYNC_IN	Sync interface	SYNC_IN accepts a trigger which sends out the latest available data message. This input is referred in software as "In 1".	
DRDY	Data ready	Data ready pin indicates that data is available (SPI / I ² C)	

2.7 Peripheral interface selection

The MTi 1-series modules are designed to be used as a peripheral devices in embedded systems. The module supports universal asynchronous receiver/transmitter (UART), inter-integrated circuit (I2C) and the serial peripheral interface (SPI) protocols. The I²C and SPI protocols are well suited for communications between integrated circuits with on-board peripherals. The MTi 1-series modules have four modes of peripheral interfacing. Only one mode can be used at a time and this is determined by the state of peripheral selection pins PSEL0 and PSEL1 at start up. Table 1 specifies how the PSEL lines select the peripheral interface. Note that the module has internal pull-ups. Not connecting PSEL results in a value of 1, connecting PSEL to a GND results in a value of 0. Examples for communication on embedded systems are available at https://developer.mbed.org/teams/Xsens.

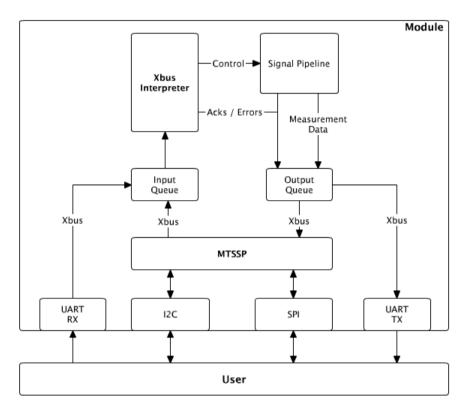
Table 1. Peripheral interface selection

Interface	PSEL0	PSEL1
l ² C	1	1
SPI	0	1
UART half-duplex	1	0
UART full-duplex	0	0

2.7.1 Peripheral Interface Architecture

At its core the module uses the Xsens-proprietary Xbus protocol which is compatible with all Xsens Motion Tracker products. This protocol is available on all interfaces, UART (asynchronous serial port interfaces) and I²C and SPI buses. The I²C and SPI buses differ from UART in that they are synchronous and have a master-slave relation in which the slave cannot send data by itself. This makes the Xbus protocol not directly transferable to these buses. For this purpose, the MTSSP protocol is introduced a protocol for exchanging standard Xbus protocol messages over the I²C and SPI buses.

The diagram below shows how MTSSP is fitted in the module's (simplified) communication architecture. The module has generic Input- and Output-Queues for Xbus protocol messages. For I²C and SPI, these messages are translated by the MTSSP layer. For the UART connection these messages are transported as-is.



2.7.2 Xbus Protocol

The Xbus protocol is Xsens' proprietary protocol that allows straightforward interfacing with the MTi 1-series. Information about the Xbus protocol can be found in the Low-Level Communication Protocol Documentation. Section 7 provides a short introduction on the Xbus protocol. It is advised to read <u>this short introduction</u> first before proceeding to the MTSSP explanation.

2.7.3 MTSSP Synchronous Serial Protocol

This communication protocol used for both I²C and SPI is called MTSSP (MTi Synchronous Serial Protocol). It is also implemented in the ARM® mbedTM example program (see <u>https://developer.mbed.org/teams/Xsens</u>)

Data flow

MTSSP communication happens according the master-slave model. The MTi 1-series module will always fulfill the slave-role while the user/integrator of the module is always the Master.

Communication is always initiated and driven by the Master; The Master either writes data to the module or the Master reads data from the module. The Master sends messages to the module in order to control it. These messages are reduced Xbus messages. A reduced Xbus message is equal to a normal Xbus message with the exception that preamble and busId are removed to save bandwidth. The calculation of the checksum is done by assuming a busId value of 0xFF (master device).

The module needs time to process the control messages it receives and will generate an acknowledge message when ready. In order to get these acknowledge messages at the Master the Master needs to read them.

The following diagram shows data flow between Master and module:

© Xsens Technologies B.V.

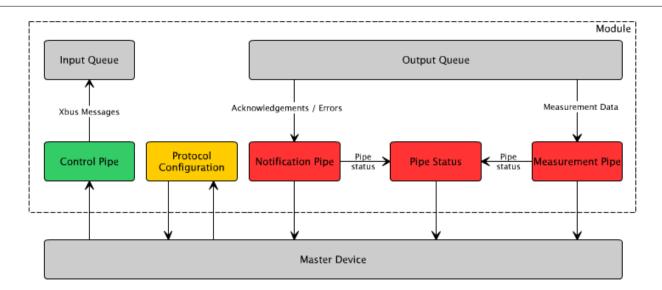


Figure 6: Data flows within MTSSP

Data ready signal

The Data Ready Signal (DRDY) is a notification line driven by the module. Its default behavior is to indicate the availability of new data in either the notification- or the measurement pipe. By default, the line is idle low and will go high when either pipe contains an item. When both pipes are empty the DRDY line will go low again. The Master can change the behavior of the DRDY signal.

The polarity can be changed to idle high, the output type can be switched between push-pull and open drain. The state of a specific pipe can be ignored. For example, it can be configured that the presence of data in the notification pipe won't influence the state of the DRDY pin.

Opcodes

The following opcodes are defined:

	g opcodes are defined.		
Opcode	Name	Read/Write	Description
0x01	ProtocolInfo	Read	Status of the protocol behaviour, protocol version
0x02	ConfigureProtocol	Write	Tweak the Protocol, e.g. the behaviour of the DRDY pin, behaviour of the pipes
0x03	ControlPipe	Write	Used to send control messages to the module
0x04	PipeStatus	Read	Provides status information for the read pipes
0x05	NotificationPipe	Read	Used to read non-measurement data: errors acknowledgements and other notifications from the module
0x06	MeasurementPipe	Read	All measurement data generated by the module will be available in the measurement pipe

ProtocolInfo (0x01)

The Protocollnfo opcode allows the Master to read the active protocol configuration. The format of the message is as follows (All data is little endian, byte aligned):

```
struct MtsspInfo
{
    uint8_t m_version;
    uint8_t m_drdyConfig;
```

};

m version

7	6	5	4	3	2	1	0
			VE	RSION [7:0]			
m drdy	YConfig						

Bits 7:	4 Reserved for future use
Bit 3	MEVENT : Measurement pipe DRDY event enable 0 : Generation of DRDY event is disabled 1 : Generation of DRDY event is enabled
Bit 2	NEVENT : Notification pipe DRDY event enable 0 : Generation of DRDY event is disabled 1 : Generation of DRDY event is enabled
Bit 1	OTYPE : Output type of DRDY pin 0: Push/pull 1: Open drain
Bit 0	POL : Polarity of DRDY signal 0: Idle Iow 1: Idle high

ConfigureProtocol (0x02)

The ProtocolInfo opcode allows the Master to change the active protocol configuration. The format of the message is as follows (All data is little endian, byte aligned):

```
struct MtsspConfiguration
{
```

```
uint8_t m_drdyConfig;
```

};

m drdyConfig

Bits 7:4	Reserved for future use
Bit 3	MEVENT : Measurement pipe DRDY event enable 0 : Generation of DRDY event is disabled 1 : Generation of DRDY event is enabled
Bit 2	NEVENT : Notification pipe DRDY event enable 0 : Generation of DRDY event is disabled 1 : Generation of DRDY event is enabled
Bit 1	OTYPE : Output type of DRDY pin 0: Push/pull 1: Open drain
Bit 0	POL : Polarity of DRDY signal 0: Idle high 1: Idle low

ControlPipe (0x03)

The ControlPipe opcode allows the Master to write messages to the control pipe. The bytes following the opcode are interpreted as a single (reduced) Xbus message

PipeStatus (0x04)

The PipeStatus opcode allows the Master to retrieve the status of the module's Notification- and Measurement pipes. The format of the message is as follows (All data is little endian, byte aligned):

```
struct MtsspConfiguration
{
    uint16_t m_notificationMessageSize;
    uint16_t m_measurementMessageSize;
};
```

NotificationPipe (0x05)

The NotificationPipe opcode is used to read from the notification pipe. The read data is a single reduced Xbus message

MeasurementPipe (0x06)

The MeasurementPipe opcode is used to read from the measurement pipe. The read data is a single reduced Xbus message

2.7.4 I²C

The MTi 1-series supports the l^2C transport layer as of firmware 1.0.6. Note that devices with firmware revision 1.0.3 and lower cannot be upgraded to support this protocol.

The MTi 1-series module acts as an I²C Slave. The Master is defined as the user of the MTi 1-series module.

The I^2C slave address is determined by the ADD0, ADD1 and ADD2 pins. These pins are pulled-up internally so when left unconnected the address selection defaults to ADD[0..2] = 111.

Note: when the module is in the Development Kit, the I²C address connections cannot be left unconnected.

Table 2. List of I²C addresses

I ² C address	ADD0	ADD1	ADD2
0x1D	0	0	0
0x1E	1	0	0
0x28	0	1	0
0x29	1	1	0
0x68	0	0	1
0x69	1	0	1
0x6A	0	1	1
0x6B (default)	1	1	1

Table 3. Implemented I²C bus protocol features

Feature	Slave Requirement	MTi 1-series
7-bit slave address	Mandatory	Yes
10-bit slave address	Optional	No
Acknowledge	Mandatory	Yes
Arbitration	N/A	N/A
Clock stretching	Optional	Yes ³
Device ID	Optional	No
General Call address	Optional	No
Software Reset	Optional	No
START byte	N/A	N/A
START condition	Mandatory	Yes
STOP condition	Mandatory	Yes
Synchronization	N/A	N/A

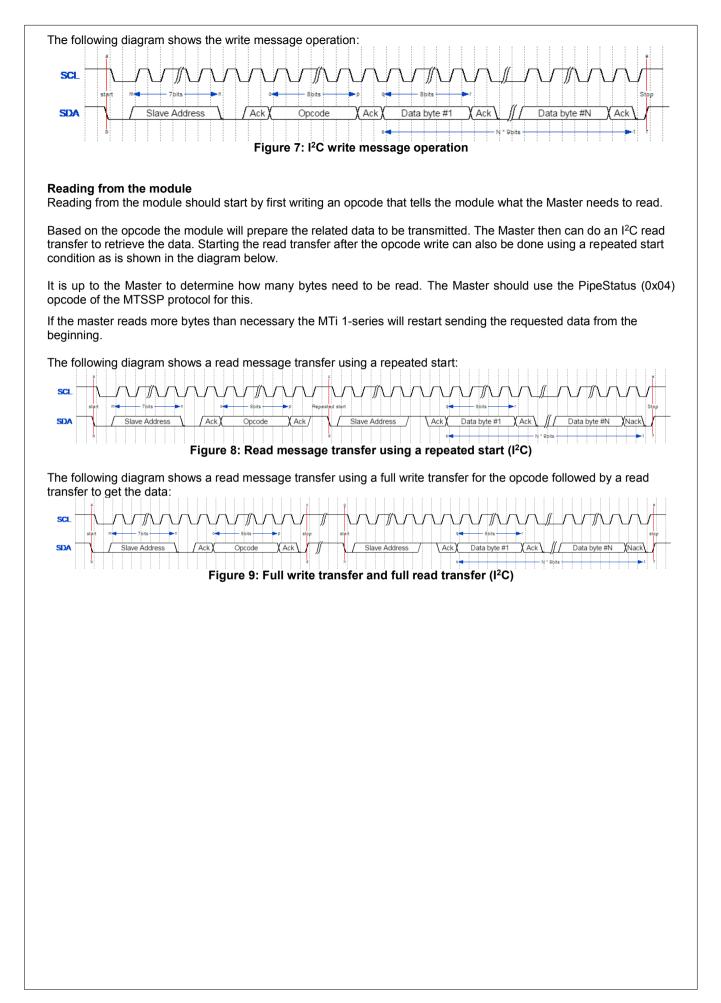
Writing to the module

Write operations consists of a single I²C write transfer. The Master addresses the MTi 1-series and the first byte that is sent is interpreted by the module as the opcode. The following bytes are considered the actual message. The actual handling of the received message by the module is determined by the opcode.

The maximum message size a module can receive is 512 bytes. If the Master sends more than 512 bytes the module will reset its receive-buffer which reduces the received message to consist only of the excess bytes.

www.xsens.com

³ The MTi-1 module relies on the I²C clock stretching feature to overcome fluctuations in processing time, the Master is required to support this feature



2.7.5 SPI

The MTi 1-series supports the SPI transport layer as of firmware 1.0.6. Note that devices with firmware revision 1.0.3 and lower cannot be upgraded to support this protocol.

The MTi 1-series module acts as an SPI Slave. The Master is defined as the user of the MTi 1-series module.

SPI Configuration

The MTi 1-series supports 4-wire mode SPI. The four lines used are:

- Chipselect (SPI nCS)
- Serial Clock (SPI SCK)
- Master data in, slave data out (SPI_MISO)
- Master data out, slave data in (SPI MOSI)

The module uses SPI mode 3; Data is captured on the rising clock edge and data is latched/propagated on the falling clock edge. (CPOL=1 and CPHA=1);

Data is clocked-out MSB first. The module uses an 8-bit data format

Data transfer

There is a single type of SPI transfer used for all communications. The diagram below shows the basic transfer.

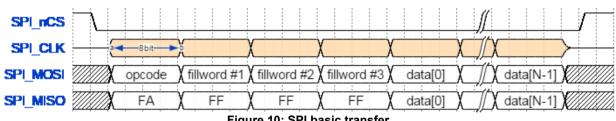


Figure 10: SPI basic transfer

A transfer is started selecting the Slave by pulling the SPI nCS low. The SPI nCS line is to be kept low for the duration of the transfer. The Slave will interpret the rising edge of the SPI_nCS line as the end of the transfer The Master places the data it needs to transmit on the SPI MOSI line. The Slave will place its data on the SPI MISO line.

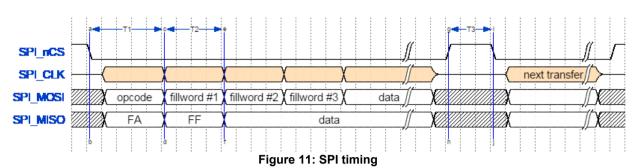
The first byte transmitted by the Master is the opcode which identifies what kind of data is transmitted by the Master and what kind of data the Master wants to read from the Slave (See MTSSP).

The second- to fourth byte transmitted are the fill words. These fill words are needed to give the Slave some time to prepare the remainder of the transfer. In principal the Slave is free to choose the value of the fill word; and its value should therefore be ignored by the Master. However the first 4 bytes transmitted by the MTi 1-series module are always 0xFA, 0xFF, 0xFF, 0xFF.

Following the first four words are the actual data of the transfer. It is the responsibility of the Master to determine how many bytes need to be transferred. The Master should use the PipeStatus (0x04) opcode of the MTSSP protocol for this.

Timing

The following timing constraints apply to the SPI transport layer.



Symbol	Parameter	Conditions	Unit	Min	Тур	Max
T1	Slave select to first complete word delay		μs	4		
T2	Byte time		μs	4		
Т3	Consecutive SPI transfer guard time		μs	3		
	Max SPI bitrate		Mbit			2

2.7.6 UART half duplex

The MTi 1-series module can be configured to communicate over UART in half duplex mode. The UART frame configuration is 8 data bits, no parity and 1 stop bit (8N1). In addition to the RX and TX pins the control lines nRE and DE are used. These control outputs are used to drive the TX signal on a shared medium and to drive the signal of the shared medium on the RX signal.

A typical use case for this mode is to directly drive a RS485 transceiver where the shared medium is the RS485 signal and nRE and DE lines control the buffers inside the transceiver.

When the MTi is transmitting data on its TX pin it will raise both the nRE and DE lines, else it will pull these lines low.

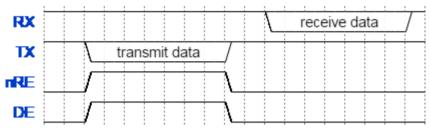


Figure 12 Behaviour of the nRE and DE lines

Note that in this mode the UART of the MTi 1-series itself is still operating full duplex.

UART full duplex with RTS/CTS flow control 2.7.7 The MTi 1-series module can be configured to communicate over UART in full duplex mode with RTS/CTS flow control. The UART frame configuration is 8 data bits, no parity and 1 stop bit (8N1). In addition to the RX and TX signals for data communication the RTS and CTS signals are used for hardware flow control. The CTS signal is an input for the MTi. The MTi checks the state of the CTS line at the start of every byte it transmits. If CTS is low the byte will be transmitted. Otherwise transmission is postponed until CTS is lowered. When during the transmission of a byte the CTS signal is raised then the transmission of that byte is completed before postponing further output. This byte will not be retransmitted. This behaviour is shown in the following image: CTS start Byte N+1 TX Byte N stop start stop Figure 13 Data transmit behaviour under CTS The RTS signal is an output for the MTi. If the RTS line is high, the MTi is busy and unable to receive new data. Otherwise the MTi-1 series UART is idle and ready to receive. After receiving a byte the DMA controller of the MTi will transfer the byte to its receive FIFO. The RTS signal will be asserted during this transfer. So with every byte received the RTS line is raised shortly like shown in the following image: RTS Byte N+1 RX Byte N start stop start stop Figure 14 RTS behaviour under data reception

This communication mode can be used without hardware flow control. In this case the CTS line needs to be tied low (GND) to make the MTi transmit.

2.8 Recommended external components

Component	Description	Typical value
R _{pu}	I ² C pull-up resistor	2.7 kΩ

Notes:

- R_{pu} is only needed when the MTi-1 is configured for I²C interface
- R_{PSEL} is only required when interface is not I²C.

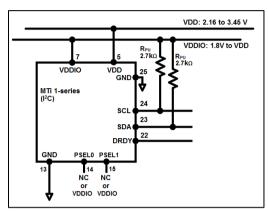


Figure 15: External components (I²C interface)

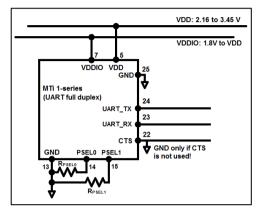


Figure 16: External components (UART interface)

3 MTi 1-series architecture

This section discusses the MTi 1-series architecture including the various configurations and the signal processing pipeline.

3.1 MTi 1-series configurations

The MTi 1-series is a fully-tested self-contained module that can output 3D orientation data (Euler angles (roll, pitch, yaw), rotation matrix (DCM) and quaternions), orientation and velocity increments (Δq and Δv) and sensors data (acceleration, rate of turn, magnetic field). The MTi 1-series module is available as an Inertial Measurement Unit (IMU), Vertical Reference Unit (VRU) and Attitude and Heading Reference System (AHRS). Depending on the product, output options may be limited to sensors data and/or unreferenced yaw.

All MTi's feature a 3D accelerometer/gyroscope combo-sensor, a magnetometer, a high-accuracy crystal and a low-power MCU. The MCU coordinates the synchronization and timing of the various sensors, it applies calibration models (e.g. temperature models) and output settings and runs the sensor fusion algorithm. The MCU also generates output messages according to the proprietary XBus communication protocol. The messages and the data output are fully configurable, so that the MTi 1-series limits the load, and thus power consumption, on the application processor.

3.1.1 MTi-1 IMU

The MTi-1 module is an Inertial Measurement Unit (IMU) that outputs 3D rate of turn, 3D acceleration and 3D magnetic field. The MTi-1 also outputs coning and sculling compensated orientation increments and velocity increments (Δq and Δv) from its AttitudeEngine[™]. Advantages over a gyroscopeaccelerometer combo-sensor are the inclusion of synchronized magnetic field data, on-board signal processing and the easy-to-use communication protocol. Moreover, the testing and calibration over temperature performed by Xsens result in a robust and reliable sensor module, that can be integrated within a short time frame. The signal processing pipeline and the suite of output options allow access to the highest possible accuracy at any output data rate, limiting the load on the application processor.

3.1.2 MTi-2 VRU

The MTi-2 is a 3D vertical reference unit (VRU). Its orientation algorithm (XKF3[™]) outputs 3D orientation data with respect to a gravity referenced frame: driftfree roll, pitch and unreferenced yaw. In addition, it outputs calibrated sensor data: 3D acceleration, 3D rate of turn and 3D magnetic field data. All modules of the MTi 1-series are also capable of outputting data generated by the strapdown integration algorithm (the AttitudeEngine[™] outputting orientation and velocity increments Δq and Δv). The 3D acceleration is also available as so-called free acceleration which has gravity subtracted. Although the yaw is unreferenced, though still superior to gyroscope integration. With the feature Active Heading Stabilization (AHS, see section 8.3) the drift in unreferenced yaw can be limited to 1 deg after 60 minutes, even in magnetically disturbed environments.

3.1.3 MTi-3 AHRS

The MTi-3 supports all features of the MTi-1 and MTi-2, and in addition is a full gyro-enhanced Attitude and Heading Reference System (AHRS). It outputs drift-free roll, pitch and true/magnetic North referenced yaw and sensors data: 3D acceleration, 3D rate of turn, as well as 3D orientation and velocity increments (Δq and Δv), and 3D earth-magnetic field data. Free acceleration is also available for the MTi-3 AHRS.

3.2 Signal processing pipeline

The MTi 1-series is a self-contained module, so all calculations and processes such as sampling, coning and sculling compensation and the Xsens XKF3[™] sensor fusion algorithm run on board.

3.2.1 Strapdown integration

The Xsens optimized strapdown algorithm (AttitudeEngine[™]) performs high-speed dead-reckoning calculations at 1 kHz allowing accurate capture of high frequency motions. This approach ensures a high bandwidth. Orientation and velocity increments are calculated with full coning and sculling compensation. At an output data rate of up to 100 Hz, no information is lost, yet the output data rate can be configured low enough for systems with limited communication bandwidth. These orientation and velocity increments are suitable for any 3D motion tracking algorithm. Increments are internally time-synchronized with the magnetometer data.

3.2.2 XKF3[™] Sensor Fusion Algorithm

XKF3 is a sensor fusion algorithm, based on Extended Kalman Filter framework that uses 3D inertial sensor data (orientation and velocity increments) and 3D magnetometer, also known as '9D' to optimally estimate 3D orientation with respect to an Earth fixed frame.

XKF3 takes the orientation and velocity increments together with the magnetic field updates and fuses this to produce a stable orientation (roll, pitch and yaw) with respect to the earth fixed frame.

The XKF3 sensor fusion algorithm can be processed with filter profiles. These filter profiles contain

predefined filter parameter settings suitable for different user application scenarios. All filter profiles can be used with Active Heading Stabilization (AHS), which significantly reduces heading drift during magnetic disturbances. In-run Compass Calibration (ICC) can be used to compensate for magnetic distortions that are caused by the object the MTi is attached to. See also section 8.3.

The following filter profiles are available:

- **General** suitable for most applications. Supported by the MTi-3 module.
- **Dynamic** assumes that the motion is highly dynamic. Supported by the MTi-3 module.
- High_mag_dep heading corrections rely on the magnetic field measured. To be used when magnetic field is homogeneous. Supported by the MTi-3 module.
- **North_reference** assumes a good MFM and a homogeneous mag field. Given stable initialization procedures and observability of the gyro bias, after dynamics this filter profile will trust more on the gyro solution and the heading will slowly converge to the disturbed mag field over the course of time. Supported by the MTi-3 module.
- VRU_general Roll and pitch are referenced to the vertical (gravity), yaw is determined by dead-reckoning. Consider using VRU_general in environments that have a heavily disturbed magnetic field. The VRU_general filter profile is the only filter profile available for the MTi-2-VRU, also supported by the MTi-3 module

3.2.3 Frames of reference used in MTi 1-series

The MTi 1-series module uses a right-handed coordinate system as the basis of the sensor of frame.

The following data is outputted in corresponding reference coordinate systems:

Data	Symbol	Reference coordinate system
Acceleration	a _x , a _y , a _z	Sensor-fixed or object frame
Rate of turn	ω _x , ω _y , ω _z	Sensor-fixed or object frame
Magnetic field	m _x , m _y , m _z	Sensor-fixed or object frame
Velocity increment	$\Delta v_{x}, \Delta v_{y}, \Delta v_{z}$	Sensor-fixed or object frame
Orientation increment	$\Delta q_0, \Delta q_1, \Delta q_2, \Delta q_3$	Sensor-fixed or object frame
Free acceleration	a _x , a _y , a _z	Local Tangent Plane (LTP), default ENU
Orientation	Euler angles, quaternions or rotation matrix	Local Tangent Plane (LTP), default ENU

Local Tangent Plane (LTP) is a local linearization of the Ellipsoidal Coordinates (Latitude, Longitude, Altitude) in the WGS-84 Ellipsoid.

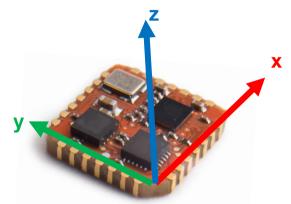


Figure 17: Default sensor fixed coordinate system for the MTi 1-series module

It is straightforward to apply a rotation matrix to the MTi, so that the velocity and orientation increments, free acceleration and the orientation output is output using that coordinate frame. The default reference coordinate system is East-North-Up (ENU) and the MTi 1-series has predefined output options for North-East-Down (NED) and North-West-Up (NWU). Any arbitrary alignment can be entered. These orientation resets have effect on all outputs that are by default outputted with an ENU reference coordinate system.

4 3D Orientation and performance specifications

4.1 3D Orientation specifications

Table 4. Orientation specifications

	Parameter	Тур	Unit	Comments
Roll/pitch	Static	0.75	deg	
	Dynamic	1.0	deg	
Yaw (heading)	Static/dynamic, Magnetic field referenced	2.0	deg	MTi-3 AHRS only in a homogenous magnetic field and a filter profile using magnetic field as reference.
	VRU_general filter profile (unreferenced yaw)	<1	deg after 60 min	Active Heading Stabilization (AHS) feature. See section 8.3 for more information.
	Output data rate	0-100	Hz	Accuracy and latency independent of output data rate. Output data rate may be any integer divider of 100 Hz or may be triggered by an external pulse ("In 1" on the SYNC_IN line)

4.2 Sensors specifications⁴

Table 5. Gyroscope specifications

Parameter	Min	Тур	Мах	Unit	Comments
Full range	±2000			deg/s	
Non-linearity		0.1		% of FS	
Sensitivity variation		0.05		%	Over temperature range
Noise density		0.01		°/s/√Hz	
g-sensitivity		0.001		deg/s/g	
In-run bias stability		10		deg/h	
Bias repeatability (1 yr)		0.5		deg/s	The bias is continuously estimated by XKF3i.
Bandwidth		180		Hz	
Natural frequency		26		kHz	This is the resonating frequency of the mass in the gyro.
Output date rate			1000	Hz	RateOfTurnHR DataID only; RateOfTurn DataID and velocity increments up to 100 Hz

Table 6. Accelerometers specifications

Parameter	Min	Тур	Max	Unit	Comments
Full range	±16			g	
Non-linearity		0.5		% of FS	
Sensitivity variation		0.05		%	Over temperature range
Noise density		200		µg/√Hz	
Zero g-output		±2		mg	
In-run bias stability		0.1		mg	
Bandwidth		180		Hz	
Output data rate			1000	Hz	AccelerationHR DataID only; Acceleration DataID and orientation increments up to 100 Hz

⁴ As Xsens continues to update the sensors on the module, these specifications may change

www.xsens.com

© Xsens Technologies B.V.

Parameter	Min	Тур	Мах	Unit	Comments
Full range	±0.8			Gauss	Magnetic fields above 0.8 Gauss are not used in XKF3. Actual full range is ±1.9 Gauss
Non-linearity		0.1		% of FS	
Noise density		200		µG/√Hz	

Table 8. Alignment specifications

Parameter	Тур	Unit	Comments
Non-orthogonality (accelerometer)	0.05	deg	
Non-orthogonality (gyroscope)	0.05	deg	
Non-orthogonality (magnetometer)	0.05	deg	
Alignment (gyr to acc)	0.05	deg	
Alignment (mag to acc)	0.1	deg	
Alignment of acc to the module board	0.2	deg	

5 Sensor calibration

Each MTi is individually calibrated and tested over its temperature range. The (simplified) sensor model of the gyroscopes, accelerometers and magnetometers can be represented as following:

$$s = K_T^{-1}(u - b_T)$$

s = sensor data of the gyroscopes, accelerometers and magnetometers in rad/s, m/s² or a.u. respectively

- K_{T} = gain and misalignment matrix (temperature compensated)
- u = sensor value before calibration (unsigned 16-bit integers from the sensor)

 b_T = bias (temperature compensated)

Xsens' calibration procedure calibrates for many parameters, including bias (offset), alignment of the sensors with respect to the module PCB and each other and gain (scale factor). All calibration values are temperature dependent and temperature calibrated. The calibration values are stored in non-volatile memory in the MTi.

6 System and electrical specifications

6.1 Interface specifications

Table 9. Communication interfaces

Interface		Min	Тур	Max	Units
l ² C	Host I ² C interface speed			400	kHz
SPI	Host SPI Interface Speed			2	MHz
	Clock Duty Sycle	30	50	70	%
UART	Baud Rates		921.6	4000	kbps

Table 10. Auxiliary interfaces

Interface		Min	Мах	Unit	Comments
SYNC_IN	VIL		0.3 * VDDIO	V	Digital input voltage
	Vih	0.45 * VDDIO + 0.3		V	Digital input voltage
	V _{HYS}	0.45 * VDDIO + 0.3		V	
nRST	VIL		0.3 * VDDIO	V	Only drive momentarily
	Rpu	30	50	kΩ	Pull-up resistor
	Generated reset pulse duration	20		μs	

6.2 System specifications

Table 11. System specifications

Interface		Min	Тур	Max		Comments
Size	Width/Length	12.0	12.1	12.2	mm	PLCC-28 compatible
	Height	2.45	2.55	2.65	mm	
Weight			0.66		gram	
Temperature	Operating temperature	-40		+85	°C	Ambient temperature, non- condensing
	Specified performance operating temperature	0		+60	°C	
Power consumption			44		mW	VDD 3.0V; VDDIO 1.8V
Timing accuracy			10		ppm	
MTBF		225,000			hours	

6.3 Electrical specifications

Table 12. Electrical specifications

	Min	Тур	Мах	Unit	Comments
VDD	2.16		3.45	V	
VDD noise			50	mVpp	
VDDIO	1.8		VDD	V	
VIL			0.3 * VDDIO	V	Digital input voltage
VIH	0.45 * VDDIO + 0.3			V	Digital input voltage
VHYS	0.45 * VDDIO + 0.3			V	Digital input voltage
Vol			0.4	V	Digital output voltage
Vон	VDDIO – 0.4			V	Digital output voltage

6.4 Absolute maximum ratings

	Min	Max	Unit	Comments
Storage temperature	-40	+125	°C	
Operating temperature	-40	+85	°C	
VDD	0.3	4.0	V	
VDDIO	0.3	VDD + 0.5	V	
SYNC_IN		5	V	
Acceleration ⁵		10,000	g	Any axis, unpowered, for 0.2 ms
ESD protection ⁶		±2000	V	Human body model

6.5 Compliance

All Xsens products, including The MTi 1-series modules and DK are RoHS compliant. The MTi 1-series modules are CE/FCC certified.

www.xsens.com

⁵ Δ This is a mechanical shock (g) sensitive device. Proper handling is required to prevent damage to the part. ⁶ \checkmark This is an ESD-sensitive device. Proper handling is required to prevent damage to the part.